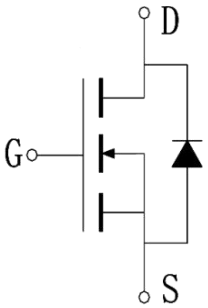
JX3090K

N-Channel Enhancement Mode MOSFET

V_{DS}	$R_{DS(on)}$ Typ.	I_D Max.
30V	3.1mΩ @ 10V	90A
	4.7mΩ @ 4.5V	



Schematic Diagram

1.Features

- 30V MOSFET technology
- Low on-state resistance
- Fast switching
- Vgs±20V

2.Applications

- Power Switching Application
- Load Switching

TO-252

Pin Description

3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
JX3090K	JX3090K	TO-252	2,500	25,000

4.Absolute Max Ratings at Ta=25℃ (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V_{DSS}	30	V
Gate to Source Voltage	V_{GSS}	±20	V
Drain Current (DC)	I_D	90	A
Drain Current (Pulse), PW≤300μs	I_{DP}	360	A
Total Dissipation	P_D	65	W
Avalanche Energy, Single Pulsed	E_{AS}	240	mJ
Junction Temperature	T_j	175	℃
Storage Temperature	T_{stg}	-55 to +175	℃

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5.Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Junction to case	$R_{\theta JC}$	2.3	℃/W

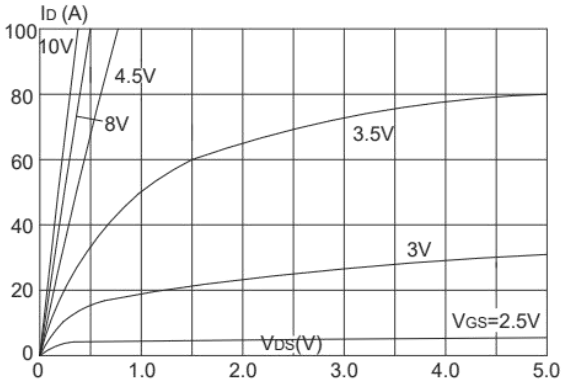
Note 2： When mounted on 1 inch square copper board t ≤ 10sec The value in any given application depends on the user's specific board design.

6.Electrical Characteristics at Ta=25℃ (Note 3)

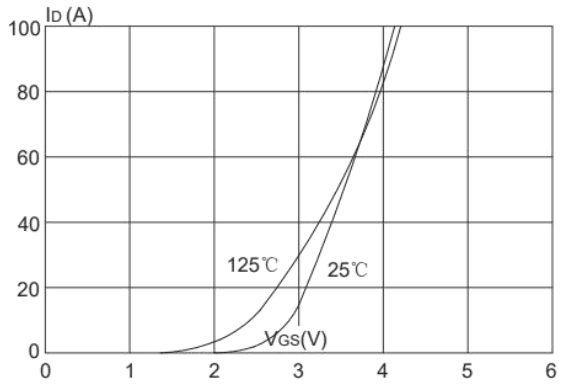
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	I_D = 250μA, V_{GS} = 0V	30			V
Zero-Gate Voltage Drain Current	I_{DSS}	V_{DS} = 30V, V_{GS} = 0V			1	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20V, V_{SS} = 0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_{DS}=250μA	1.0	1.6	2.5	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	I_D = 30A, V_{GS} = 10V	-	3.1	3.6	mΩ
		I_D = 20A, V_{GS} = 4.5V	-	4.7	7.5	mΩ
Input Capacitance	C_{iss}	V_{GS}=0V, V_{DS}=15V, Frequency=1.0MHz		1700		pF
Output Capacitance	C_{oss}			320		pF
Reverse Transfer Capacitance	C_{rss}			300		pF
Turn-ON Delay Time	$t_{d(on)}$	V_{DS} = 15V, I_D = 30A, V_{GS} = 10V, R_G = 3Ω		21		ns
Rise Time	t_r			32		ns
Turn-OFF Delay Time	$t_{d(off)}$			60		ns
Fall Time	t_f			34		ns
Total Gate Charge	Q_g	V_{DS} = 15V, V_{GS} = 10V, I_D = 30A		45		nC
	Q_{gs}			3		nC
	Q_{gd}			15		nC
Diode Forward Voltage	V_{FSD}	I_S = 30A, V_{GS} = 0	0.4	0.85	1.2	V

Note 3： Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

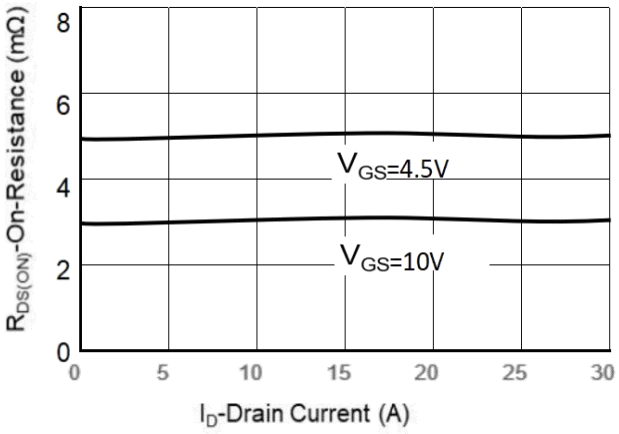
7.Typical electrical and thermal characteristics



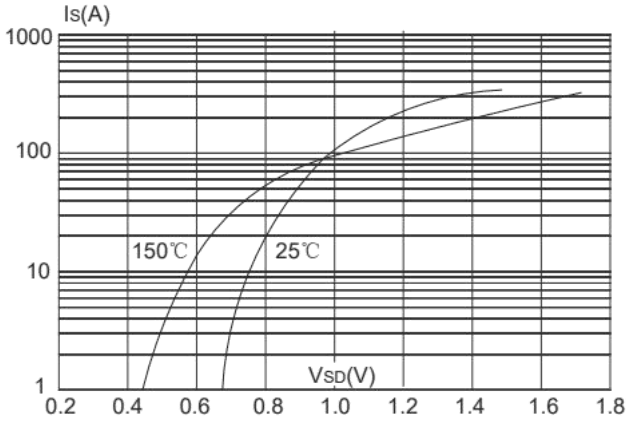
Output Characteristics



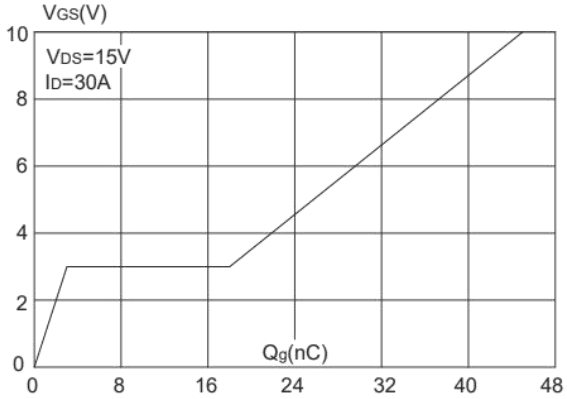
Transfer Characteristics



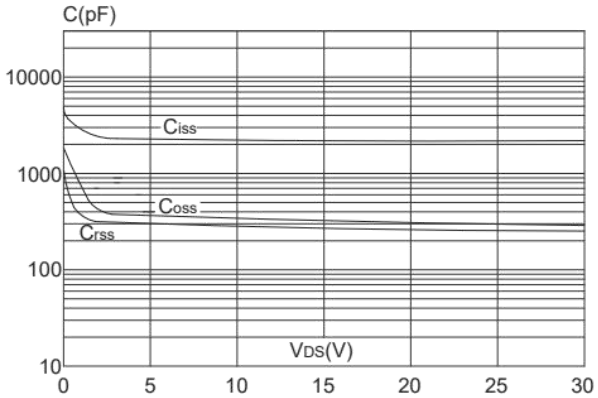
Rdson-Drain Current



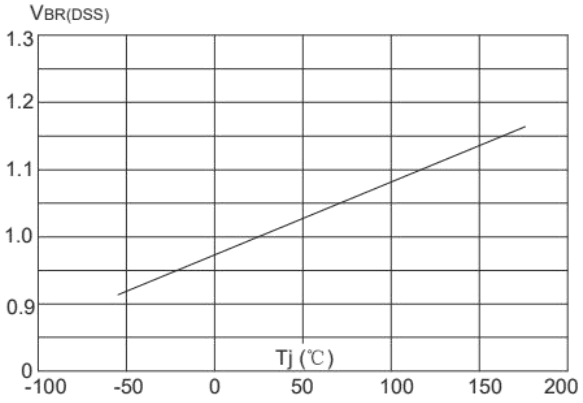
Body Diode Characteristic



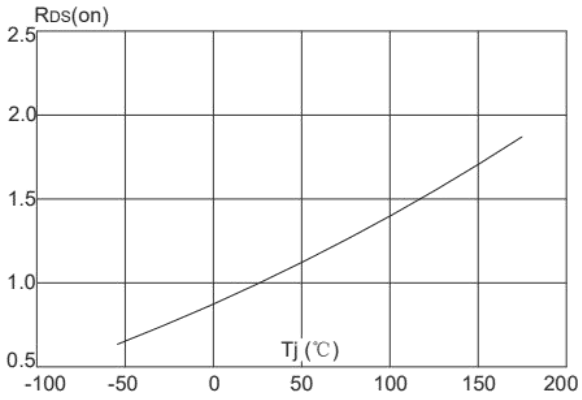
Gate Charge



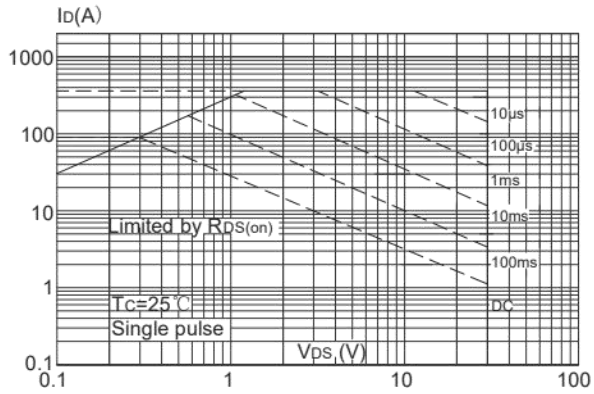
Capacitance Characteristics



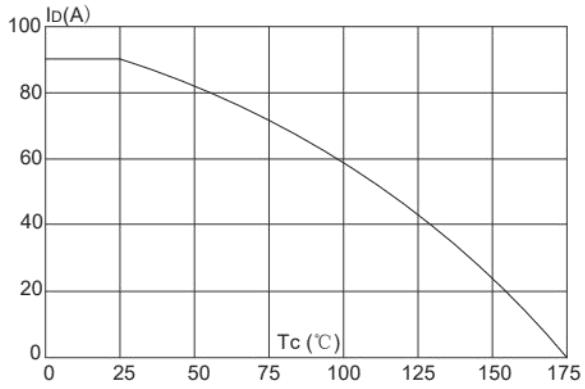
Normalized Breakdown Voltage vs. Junction Temperature



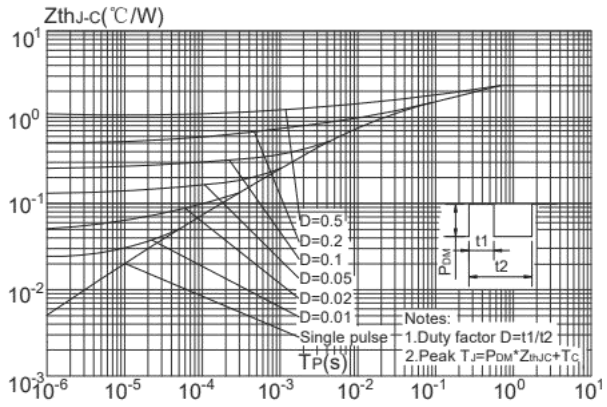
Normalized on Resistance vs. Junction Temperature



Maximum Safe Operating Area



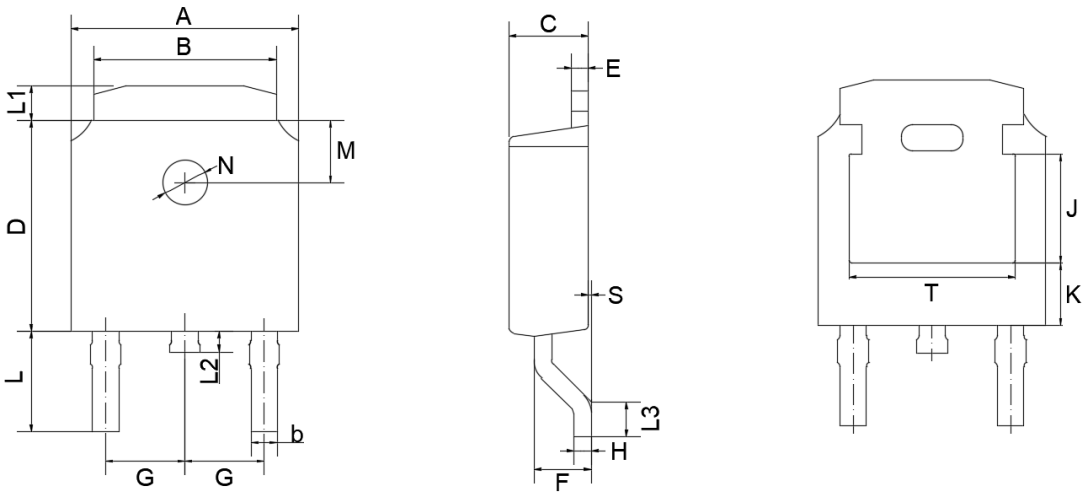
Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case

8.Package Dimensions

TO-252(D-PAK) Package Outline Dimensions



TO-252(D-PAK) mechanical data

UNIT		A	B	b	C	D	E	F	G	H	L	L1	L2	L3	S	M	N	J	K	T
mm	max	6.7	5.5	0.86	2.5	6.3	0.6	1.8	2.29 TYPICAL	0.55	3.1	1.4	1.0	1.75	0.1	1.8 TYPICAL	1.3 TYPICAL	3.16 ref.	1.80 ref.	4.83 ref.
	min	6.3	5.1	0.66	2.1	5.9	0.4	1.3		0.45	2.7	0.8	0.6	1.40	0.0					
mil	max	264	217	33	98	248	24	71	90 TYPICAL	22	122	55	39	69	4	71 TYPICAL	51 TYPICAL	124 ref.	71 ref.	190 ref.
	min	248	201	26	83	232	16	51		18	106	31	24	55	0					